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- (54) **BACKLIGHT PANEL EMPLOYING WHITE LIGHT EMITTING DIODE HAVING RED PHOSPHOR AND GREEN PHOSPHOR**
- (75) Inventors: **Seung Ryeol Ryu**, Bucheon-si (KR);  
**Seok Jin Kang**, Gwangmyeong-si (KR)
- (73) Assignee: **Seoul Semiconductor Co., Ltd.**, Seoul (KR)
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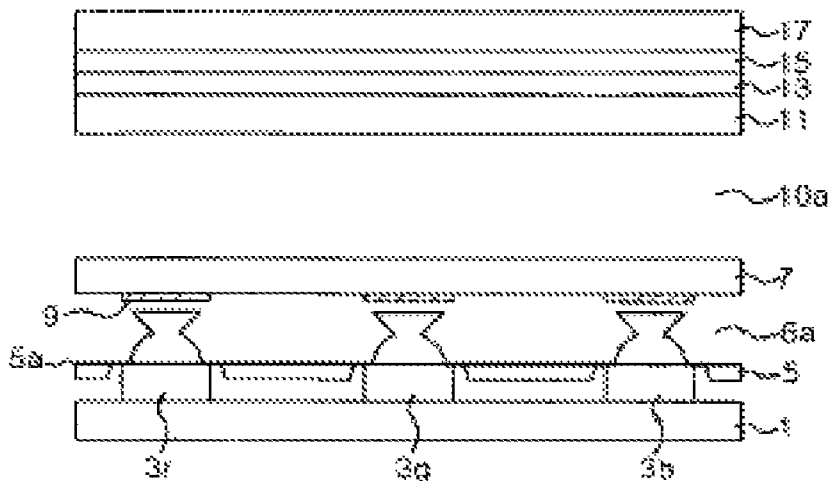
*Primary Examiner* — Ali Alavi

(74) *Attorney, Agent, or Firm* — H.C. Park & Associates, PLC

(57) **ABSTRACT**

Disclosed is a backlight panel employing a white light emitting diode. The white light emitting diode includes a blue light emitting diode chip and red and green phosphors positioned over the blue light emitting diode chip. Accordingly, since the backlighting can be performed using white light with distinct red, green and blue wavelengths, the color reproducibility can be enhanced. Further, since the white light can be implemented with a single light emitting diode, the manufacturing costs and thickness of the backlight panel can also be reduced.

**8 Claims, 2 Drawing Sheets**



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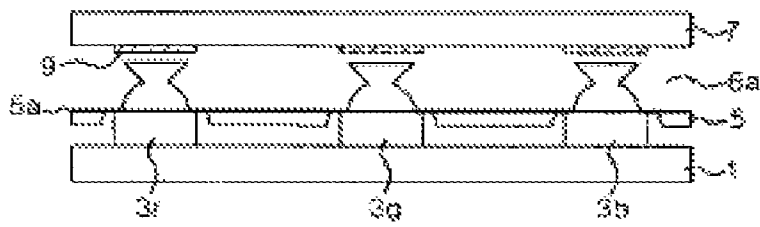
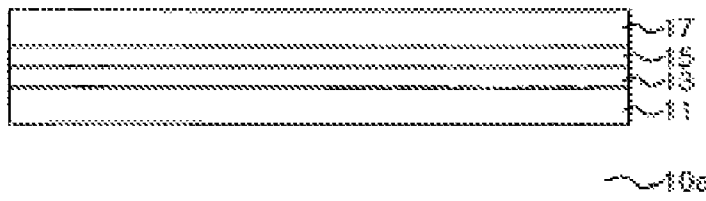
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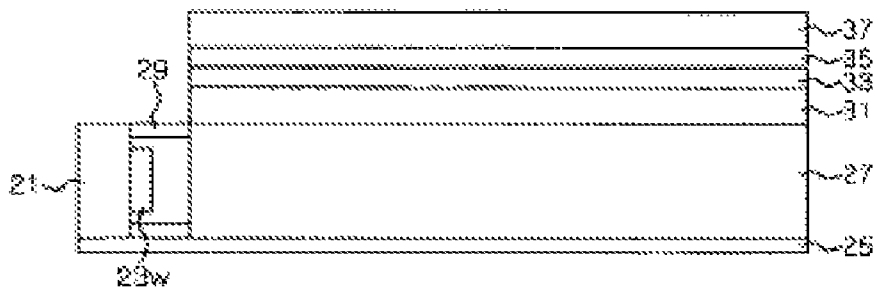
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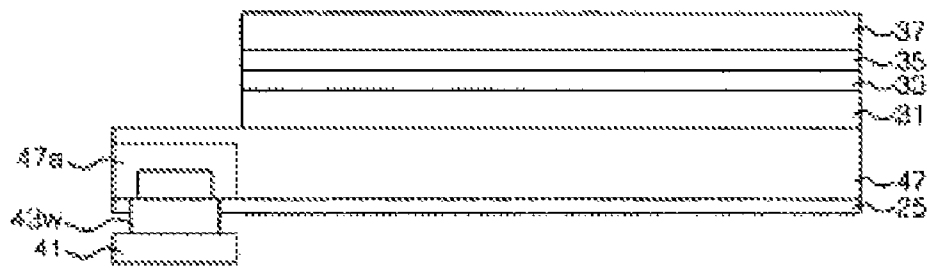
[Fig. 1]



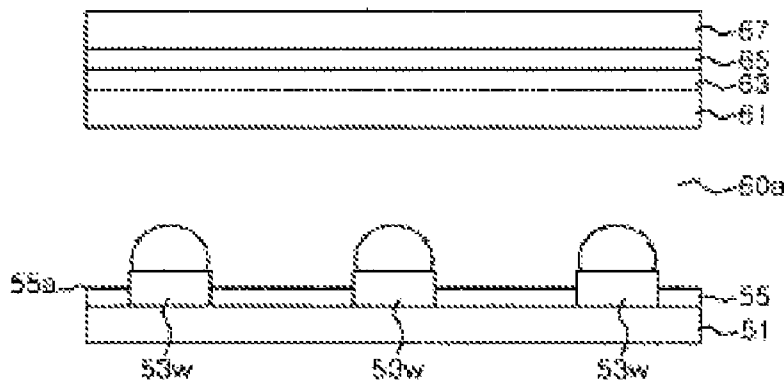
[Fig. 2]



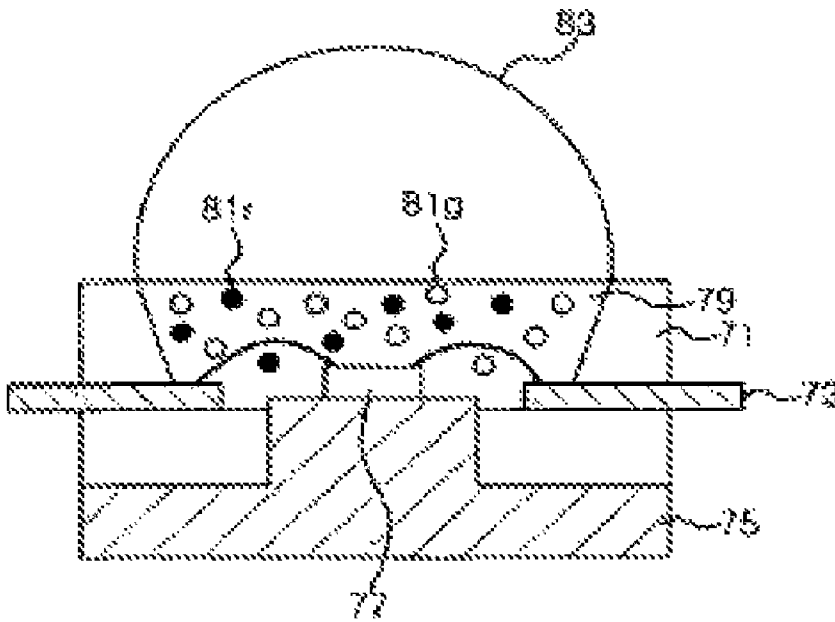
[Fig. 3]



[Fig. 4]



[Fig. 5]



## BACKLIGHT PANEL EMPLOYING WHITE LIGHT EMITTING DIODE HAVING RED PHOSPHOR AND GREEN PHOSPHOR

### CROSS-REFERENCE TO RELATED APPLICATIONS

This application is a continuation of U.S. patent application Ser. No. 11/909,700, filed on Sep. 25, 2007, which is the National Stage of International Application No. PCT/KR2006/000885, filed on Mar. 13, 2006, and claims priority from and the benefit of Korean Patent Application No. 10-2005-0027133, filed on Mar. 31, 2005, which are both hereby incorporated by reference for all purposes as if fully set forth herein.

### TECHNICAL FIELD

The present invention relates to a backlight panel for backlighting a display panel, and more particularly, to a backlight panel employing a white light emitting diode with red and green phosphors as a light source to enhance color reproducibility and luminance.

### BACKGROUND ART

A passive display device such as a liquid crystal display (LCD) reflects or absorbs ambient sunlight or indoor light to display images on an LCD panel. Thus, the ambient sunlight or indoor light is required for a user to view the displayed image. However, in a case where intensity of the ambient sunlight or indoor light is not sufficient to illuminate a display panel, there is a problem in that the user cannot view the displayed image. As an alternative to such a problem, a backlight panel for backlighting a display panel is generally employed.

A backlight panel includes a light source such as an incandescent lamp, fluorescent lamp or light emitting diode (LED). Light emitted from the light source illuminates the LCD panel, and thus, images are implemented. Meanwhile, since the LED has superior reproducibility, it has been frequently used as a backlight source. In addition, since the LED is environmentally friendly, it is expected that its use will be further increased in the future.

FIG. 1 is a partial sectional view illustrating a conventional backlight panel for backlighting an LCD panel 17 using light emitting diodes (LEDs).

Referring to FIG. 1, an LED array is arranged on a printed circuit board 1. The LED array is an array in which red, green and blue LEDs 3r, 3g and 3b are arranged at a predetermined interval. The LEDs are arranged on the printed circuit board 1 in a regular order and constructed into an LED module, and a plurality of LED modules are used to backlight the LCD panel 17.

Each of the LEDs employs a lens designed for side-luminescence such that major light can be radiated almost in a side direction.

A reflection sheet 5 is positioned below light exit surfaces of the LEDs. The reflection sheet may be formed with a reflection layer 5a on the top thereof. The reflection sheet reflects light emitted from the LEDs in an upward direction.

Furthermore, a light transmission layer 7 is positioned above the LEDs. The light transmission layer is a layer through which light emitted from the LED can be transmitted. The light transmission layer is generally made of a transparent resin such as PMMA (poly methyl methacrylate). The light transmission layer 7 is provided with light shielding

patterns 9 at positions corresponding to the LEDs. The light shielding patterns function to prevent light emitted upward from the LEDs from penetrating the light transmission layer and then traveling toward the LCD panel 17. The light shielding patterns may be formed through an ESR (electroslag remelting) process.

The light transmission layer 7 and the reflection sheet 5 are spaced apart at a predetermined interval to define a first gap 6a which is an air layer. The first gap is a region where red, green and blue light emitted respectively from the LEDs 3r, 3g and 3b are mixed with one another.

A diffusion plate 11 is positioned above and spaced apart from the light transmission layer 7. The diffusion plate 11 diffuses light incident thereon to make the light uniform. The diffusion plate and the light transmission layer 7 are spaced apart from each other by a predetermined interval to define a second gap 10a which is an air layer. Thus, the light transmitted through the light transmission layer 7 is again mixed within the second gap 10a and the mixed light is then incident onto the diffusion plate 11.

A brightness enhancement film (BEF) 13 such as a prism sheet is positioned on a top surface of the diffusion plate 11. The BEF may be composed of two sheets which have upward prisms formed in longitudinal and transverse directions, respectively. In addition, a dual brightness enhancement film (DBEF) 15 such as a dual brightness enhancement film-embossed (DBEF-E) is positioned on a top surface of the BEF 13. The BEFs 13 and 15 refract light emitted at a large showing angle from the diffusion plate 11 into light with a small showing angle such that the light can be incident onto the LCD panel 17. Accordingly, the luminance of the LCD panel is increased.

Since the red, green and blue LEDs are used as light sources according to a prior art, the color reproducibility can be enhanced. However, it is necessary to mix light emitted from the LEDs in order to obtain the uniform light. Accordingly, it is necessary to prevent light emitted from the LEDs from transmitting directly through the light transmission layer 7 and traveling toward the diffusion plate 11 by using the light shielding pattern 9. Further, air layers such as the first and second gaps 6a and 10a are required. These result in an increase in thickness of a backlight panel.

Further, while light emitted from the LEDs is mixed, light loss is generated. Thus, such light loss should be compensated by increasing an amount of current supplied to the LEDs, by using a larger number of LEDs or by using the BEF 13, the DBEF 15 and the like. However, in a case where the amount of current is increased or a large number of LEDs are used, power consumption is increased. In particular, the increase in the amount of current leads to an increase of heat generated from the LEDs, and the light shielding layer may be deteriorated. In addition, the use of the BEFs causes the total thickness of the backlight panel to be further increased and the manufacturing costs of the backlight panel to be increased.

### TECHNICAL PROBLEM

An object of the present invention is to provide a backlight panel which has smaller thickness and reduced manufacturing costs as compared with a conventional backlight panel.

Another object of the present invention is to provide a backlight panel capable of enhancing its luminance as compared with a conventional backlight panel.

### TECHNICAL SOLUTION

In order to achieve the above objects of the present invention, there is provided a backlight panel employing a white

light emitting diode with red and green phosphors. A backlight panel according to an aspect of the present invention comprises a light guide plate for emitting light incident from a side direction. The light guide plate emits light through a top surface thereof. The white light emitting diodes are arranged at a side of the light guide plate to emit white light into the light guide plate. Each of the white light emitting diodes includes a blue light emitting diode chip and red and green phosphors positioned over the blue light emitting diode chip. Furthermore, a diffusion plate is positioned over the top surface of the light guide plate. Therefore, the color reproducibility of a liquid crystal display can be ensured and the thickness of the backlight panel can also be reduced, by employing the white light emitting diode with three red, green and blue wavelengths.

Further, a brightness enhancement film and/or a dual brightness enhancement film may be positioned over the diffusion plate. The brightness enhancement films can enhance the luminance of the backlight panel.

A backlight panel according to another aspect of the present invention comprises a diffusion plate having a top surface and a bottom surface. White light emitting diodes are arranged below the bottom surface of the diffusion plate at a predetermined interval from the diffusion plate. Each of the white light emitting diodes includes a blue light emitting diode chip and red and green phosphors positioned over the blue light emitting diode chip. Furthermore, a reflection sheet is positioned below light exit surfaces of the white light emitting diodes and also allows light traveling in a direction opposite to the diffusion plate to be reflected toward the diffusion plate. Therefore, the color reproducibility of a liquid crystal display can be ensured and spaces or gaps where light is mixed can also be reduced, so that the thickness of the backlight panel can be reduced. Further, since the luminance can be enhanced with the use of a light source for upward emitting light, brightness enhancement films can be omitted.

In addition, a brightness enhancement film and/or a dual brightness enhancement film may be positioned over the diffusion plate to further increase the luminance of the backlight panel.

Preferably, the red phosphor of the present invention is a phosphor that is excited by blue light emitted from the blue light emitting diode chip to radiate red light. The red phosphor may be an alkali earth metal sulfide-based red phosphor expressed as general formula,  $A_{x-a}Eu_aGeS_z$ , where A is at least one element selected from the group consisting of Ca and Sr;  $z=x+2$ ; x is set within a range of about 2 to about 5; and  $a/x$  is set within a range of about 0.0005 to about 0.02.

Preferably, the green phosphor of the present invention is a phosphor that is excited by blue light emitted from the blue light emitting diode chip to radiate green light. The green phosphor may be a thiogallate-based green phosphor expressed as general formula,  $(A_{1-x-y}Eu_x(M^I_{0.5}M^{III}_{0.5}))_y B_2S_4$ , where  $0 < x, y, x+y < 1$ ; A is at least one element selected from the group consisting of Ba, Sr and Ca; B is at least one element selected from the group consisting of Al, Ga and In; x is set within a range of about 0.01 to about 0.1;  $M^I$  is at least one element selected from the group consisting of Li, Na and K;  $M^{III}$  is at least one element selected from the group consisting of Sc, Y, Lu, Gd and La; and y is set within a range of about 0.2 to about 0.8.

#### ADVANTAGEOUS EFFECTS

According to the embodiments of the present invention, there is provided a backlight panel which has smaller thickness and reduced manufacturing costs as compared with the

conventional backlight panel. Further, there is provided a backlight panel having enhanced luminance as compared with the conventional backlight panel.

Meanwhile, in a case where the red, green and blue LEDs are used as described in the prior art, the life spans and degrees of deterioration of the LEDs are different from one another. Thus, a color sensor should be installed on the LCD panel to detect the deterioration of the LEDs and to perform a compensation work. However, since the white LEDs of the same kinds are used in the embodiments of the present invention, the life spans and deterioration of the LEDs are generally similar to one another. Therefore, it is less necessary to use the color sensor and perform the compensation work. Accordingly, an operation circuit of the LCD panel can be further simplified.

#### DESCRIPTION OF DRAWINGS

FIG. 1 is a sectional view illustrating a conventional backlight panel.

FIG. 2 is a sectional view illustrating a backlight panel according to an aspect of the present invention.

FIG. 3 is a sectional view illustrating another embodiment of the backlight panel according to the aspect of the present invention.

FIG. 4 is a sectional view illustrating a backlight panel according to another aspect of the present invention.

FIG. 5 is a sectional view illustrating a white light emitting diode of the present invention.

#### MODE FOR INVENTION

Hereinafter, preferred embodiments of the present invention will be described in detail with reference to the accompanying drawings. The following embodiments are provided only for illustrative purposes so that those skilled in the art can fully understand the spirit of the present invention. Therefore, the present invention is not limited to the following embodiments but may be implemented in other forms. In the drawings, the widths, lengths, thicknesses and the like of components may be exaggerated for convenience of illustration. Like reference numerals indicate like elements throughout the specification and drawings.

FIG. 2 is a sectional view illustrating a backlight panel for backlighting a liquid crystal display panel 37 (hereinafter, referred to as "LCD panel") according to an aspect of the present invention.

Referring to FIG. 2, a light guide plate 27 is positioned below the LCD panel 37. The light guide plate converts light emitted from a light source 23w into surface light and then emits the surface light upward toward the LCD panel. The light guide plate 27 may be made of glass, a transparent resin such as a transparent acrylic resin or a polycarbonate or epoxy resin, or the like. Both surfaces of the light guide plate may be machined with a variety of patterns such as V-shaped grooves, lens shapes, prism shapes or hologram patterns, if necessary. Further, a reflection sheet 25 may be positioned on a bottom surface of the light guide plate.

White light emitting diodes (hereinafter, referred to as "LEDs") are positioned adjacent to a side of the light guide plate. Each of the white LEDs emits white light toward the side of the light guide plate 27. The white LED may be mounted on a printed circuit board 21, and a plurality of LEDs may be mounted on the printed circuit board 21 as an LED module. The LEDs 23w mounted on the printed circuit board 21 may be simultaneously driven through a circuit printed on the printed circuit board. Meanwhile, the LEDs may be posi-

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tioned at both sides of the light guide plate 27. Accordingly, the luminance of the LCD panel 37 can be further enhanced.

The white LED 23<sub>w</sub> includes a blue LED chip, and green and red phosphors which are positioned over the blue LED chip to convert a portion of blue light into green and red light, respectively. The white LED 23<sub>w</sub> will be described in detail later with reference to FIG. 5.

Meanwhile, light shielding walls 29 are positioned above and below the white LED 23<sub>w</sub>, respectively. The light shielding walls prevent light emitted from the white LED 23<sub>w</sub> from traveling toward regions other than the side of the light guide plate 27. A reflection layer is coated on an inner wall of the light shielding wall 29 to enable light incident onto the light shielding wall to be reflected. Such a reflection layer may be also formed on a top surface of the printed circuit board 21.

A diffusion plate 31 is positioned over top surface of the light guide plate 27. The diffusion plate 31 may be a thin sheet. The diffusion plate 31 diffuses light incident from the light guide plate 27 into uniform light. Moreover, a brightness enhancement film (BEF) 33 and/or a dual brightness enhancement film (DBEF) 35 may be interposed between the diffusion plate 31 and the LCD panel 37. The BEFs 33 and 35 collect light emitted from the light guide plate 27 within a certain showing angle to increase the luminance of light.

Since the backlight panel according to the aspect of the present invention is mounted with the white LED to enable uniform white light to be emitted from the LED, an air layer used for mixing the red, green and blue light with one another is not necessary, as compared with the prior art. Thus, the thickness of the backlight panel can be decreased. Further, since light emitted from the white LED is incident directly onto the light guide plate 27, the light emitting luminance can be enhanced. Thus, the BEFs 33 and 35 may be omitted. Furthermore, in a case where the BEFs are used, the luminance can be further enhanced. Thus, the number of LEDs used can also be reduced.

FIG. 3 is a sectional view illustrating another embodiment of the backlight panel according to the aspect of the present invention.

Referring to FIG. 3, the diffusion plate 31, the BEFs 33 and 35, and the LCD panel 37 are provided in the same manner as described with reference to FIG. 2. Hereinafter, only differences between the backlight panels of FIGS. 2 and 3 will be described in detail.

A light guide plate 47 is positioned below the diffusion plate 31. The light guide plate 47 is formed with a receiving groove 47<sub>a</sub> at a side thereof to accommodate LEDs in the receiving groove. As described with reference to FIG. 2, the light guide plate 47 may be made of glass, a transparent resin such as a transparent acryl resin or a polycarbonate or epoxy resin, or the like. Further, both surfaces of the light guide plate may be machined with a variety of patterns such as V-shaped grooves, lens shapes, prism shapes or hologram patterns, if necessary. Furthermore, the reflection sheet 25 can be positioned on a bottom surface of the light guide plate. The reflection sheet 25 may be attached to the bottom surface of the light guide plate 47 to extend to the side thereof and have a through-hole through which the LEDs can be received in the receiving groove 47<sub>a</sub> of the light guide plate 47.

A white LED 43<sub>w</sub> is accommodated in the receiving groove 47<sub>a</sub>. The white LED is a side-view LED which emits light almost in parallel with top and bottom surfaces of the light guide plate 47, i.e. perpendicular to the side surfaces thereof. The side-view LED can adjust a showing angle of emitted light to be smaller than that of an LED emitting light upward, so that the thickness of the light guide plate 47 can be reduced.

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The white LED may be mounted on a printed circuit board 41, and a plurality LEDs may also be mounted on the printed circuit board 41 as an LED module. The LEDs 43<sub>w</sub> mounted on the printed circuit board 41 may be simultaneously driven through a circuit printed on the printed circuit board. Meanwhile, the LEDs may be positioned at both sides of the light guide plate 47. Accordingly, the luminance of the LCD panel 37 can be further enhanced.

According to this embodiment, the side-view LED capable of adjusting a showing angle to be smaller is mounted such that the thickness of the light guide plate can be reduced.

FIG. 4 is a sectional view illustrating a backlight panel according to another aspect of the present invention.

Referring to FIG. 4, a diffusion plate 61 is positioned below an LCD panel 67. The diffusion plate has a top surface and a bottom surface. BEF 63 and/or DBEF 65 may be interposed between the diffusion plate and the LCD panel 67.

Meanwhile, white LEDs 53<sub>w</sub> are arranged below the bottom surface of the diffusion plate 61 at a certain interval from the diffusion plate 61. Each of the white LEDs 53<sub>w</sub> includes a blue LED chip, and green and red phosphors positioned over the blue LED chip. The white LEDs 53<sub>w</sub> will be described in detail later with reference to FIG. 5.

Each of the white LEDs 53<sub>w</sub> emits white light toward the diffusion plate 61. The white LED may be mounted on a printed circuit board 51, and a plurality LEDs may be mounted on the printed circuit board 51 as an LED module. The LEDs 53<sub>w</sub> mounted on the printed circuit board 51 may be simultaneously driven through a circuit printed on the printed circuit board. A plurality of LED modules may be arranged below the diffusion plate 61 to uniformly backlight the LCD panel 67.

Furthermore, a reflection sheet 55 is positioned below light exit surfaces of the white LEDs 53<sub>w</sub>. The reflection sheet 55 may be formed with a reflection layer 55<sub>a</sub> thereon. The reflection sheet may be made of an aluminum sheet and coated with the reflection layer 55<sub>a</sub> thereon. Further, the reflection sheet 55 may be attached onto the printed circuit board 51 as shown in this figure.

The reflection sheet 55 and the diffusion plate 61 are spaced apart from each other by a predetermined interval to define a gap 60<sub>a</sub> corresponding to an air layer. White light emitted from the white LEDs 53<sub>w</sub> are mixed with one another in the gap 60<sub>a</sub> and then incident onto the diffusion plate 61.

The backlight panel according to this aspect does not use an additional light guide plate. Thus, the diffusion plate 61 may be thicker than the diffusion plate 31 of FIG. 2 or 3 such that light emitted from the white LEDs 53<sub>w</sub> can be uniform.

In the meantime, since the backlight panel according to this aspect employs top-view white LEDs contrary to the prior art, the light transmission layer 7 (FIG. 1) formed with the light shielding pattern 9 (FIG. 1) may be omitted. Further, since light emitted from the white LEDs 53<sub>w</sub> is incident directly onto the diffusion plate 61, the light loss can be reduced so that the luminance of the LCD panel 67 can be enhanced. Accordingly, since the BEF 63 and the DBEF 65 can be omitted, the thickness of the backlight panel can also be reduced. FIG. 5 is a sectional view illustrating the white LED 23<sub>w</sub>, 43<sub>w</sub> or 53<sub>w</sub> used in the embodiments of the present invention.

Referring to FIG. 5, the white LED includes a package body 71. The package body may be formed using an injection molding, pressing or machining technique, and particularly injection-molded using a plastic resin. The package body is formed with a cavity which exposes lead terminals 73. Further, a sidewall of the cavity may be an inclined surface inclined at a certain angle.



The lead terminals **73** extend outward to protrude out of the package body **71**. The lead terminals **73** protruding to the outside are connected to a printed circuit board and electrically connected to an external power source. The lead terminals **73** may be bent from the outside such that they can be surface mounted.

Meanwhile, a heat sink **75** may be attached to the bottom of the package body **71**. The heat sink is provided to easily dissipate heat generated from an LED chip **77** to the outside. The heat sink **75** may be formed with a base and a projection protruding upward from a center portion of the base. The projection is inserted into the package body and then exposed to the cavity. After the package body **71** has been formed with a through-hole, the heat sink can be inserted into the through-hole of the package body and mounted to the package body. Alternatively, the heat sink **75** can be attached to the package body **71** by positioning the lead terminals **73** and the heat sink **75** and then forming the package body using an insert-molding technique. The heat sink **75** may be electrically isolated from the lead terminals **75**, or electrically connected to any one of the lead terminals.

A blue LED chip **77** for emitting blue light is mounted on the heat sink **75**. The LED chip **77** is a GaN, InGaN or AlGaInN-based light emitting diode and radiates blue light with a wavelength of about 420 to about 480 nm. The LED chip **77** has two electrodes for the connection with an external source. The electrodes may be positioned on the same side or opposite sides of the LED **77**. The electrodes may be electrically connected to the lead terminals through an adhesive or bonding wires as shown in this figure. In a case where the electrodes are formed on the same side of the LED chip, the LED chip **77** and the lead terminals are connected through the two bonding wires, respectively, so that they can be electrically connected as shown in this figure. On the other hand, in a case where the electrodes are positioned on the opposite sides, one of the electrodes is connected to the heat sink **75** using a conductive adhesive and one of the lead terminals is connected to the heat sink **75** through the bonding wire, so that the lead terminals and the LED chip **77** can be electrically connected with each other.

Over the blue LED chip **77** is positioned red and green phosphors **81r** and **81g** which are excited by blue light to radiate red and green light, respectively, such that the radiated light is mixed with a portion of blue light emitted from the LED chip **77** to become white light. The red and green phosphors may be either coated on the LED chip **77** or positioned in a molding member **79** in a state where they are contained therein as shown in this figure. The molding member **79** may be made of an epoxy or silicone resin and formed into a single layer or multiple layers.

For example, the red phosphor **81r** may be an alkali earth metal sulfide-based red phosphor, while the green phosphor **81g** may be a thiogallate-based green phosphor. More specifically, the alkali earth metal sulfide-based red phosphor is expressed as general formula  $A_{x-a}Eu_aGeS_z$ , where A is Ca and/or Sr,  $z=x+2$ , x is set within a range of 2 to 5, and  $a/x$  is set within a range of about 0.0005 to about 0.02.

Further, the thiogallate-based green phosphor is expressed as general formula  $(A_{1-x-y}Eu_x(M'_{0.5}M''_{0.5}))B_2S_4$ , where A is at least one element selected from the group consisting of Ba, Sr and Ca, B is at least one element selected from the group consisting of Al, Ga and In, and  $0 < x, y, x+y < 1$ . Preferably, x is set within a range of about 0.01 to about 0.1. Meanwhile,  $M'$  is at least one element selected from the group consisting of Li, Na and K, and  $M''$  is at least one element selected from the group consisting of Sc, Y, Lu, Gd and La. Preferably, y is set within a range of about 0.2 to about 0.8.

Such red and green phosphors **81r** and **81g** are obtained in the following manners. That is, phosphor raw materials and an activator raw material are weighted to have a predetermined mixing ratio in accordance with a desired composition and sufficiently mixed into a uniform mixture by using a ball milling or a mixer such as agate mortar within an alcohol solvent for effective mixing. Then, the mixture is dried in an oven at a temperature of about 100 to about 150° C. for about 1 to 2 hours. The dried mixture is heat-treated in a high-purity alumina boat at a temperature of about 800 to about 1300° C. under the atmosphere of  $H_2S$  using an electric furnace to synthesize phosphor powder and then sufficiently pulverize the synthesized phosphor powder.

According to the results of measuring photoluminescence (PL) of the powder, the thiogallate-based green phosphor of a typical composition expressed as  $Sr_{0.36}Eu_{0.04}Y_{0.3}Li_{0.3}Ga_2S_4$  exhibits strong photoluminescence spectrum throughout a region of 470 to 630 nm while the alkali earth metal sulfide-based red phosphor expressed as  $Sr_{2.185}Eu_{0.015}Ca_{0.8}GeS_5$  exhibits strong photoluminescence spectrum throughout a region of 520 to 780 nm. Accordingly, white light with distinct red, green and blue wavelengths can be radiated using the blue LED chip **77** and the phosphors, and thus, the color reproducibility of the LCD panel can be enhanced.

Meanwhile, the LED chip **77** and the phosphors **81r** and **81g** are covered with a lens **83**. The lens may be formed into a variety of shapes. For example, to implement a top-view LED according to the aspects of the present invention, the lens may take the shape of a convex lens as shown in this figure. At this time, the curvature of the lens is determined depending on a desired showing angle. Meanwhile, to implement a side-view LED shown in FIG. 2, the lens is designed to emit light from the LED chip **77** in a side direction. An example of such a side-view LED is shown in FIG. 1, and the other side-view LEDs can be implemented into a variety of lens shapes.

What is claimed is:

1. A backlight panel, comprising:

a diffusion plate comprising a top surface and a bottom surface;

a plurality of white light emitting diodes arranged below the bottom surface of the diffusion plate, the white light emitting diodes to emit light directly onto the bottom surface of the diffusion plate; and

a reflection sheet arranged below light exit surfaces of the white light emitting diodes, the reflection sheet to reflect light toward the diffusion plate, wherein each white light emitting diode comprises a blue light emitting diode chip and a red phosphor and a green phosphor arranged on the blue light emitting diode chip.

2. The backlight panel of claim 1, further comprising a brightness enhancement film and/or a dual brightness enhancement film arranged on the top surface of the diffusion plate.

3. The backlight panel of claim 1, wherein the red phosphor comprises an alkaline earth metal sulfide-based phosphor expressed by the general formula:  $A_{x-a}Eu_aGeS_z$ , where A is at least one element selected from the group consisting of Ca and Sr;  $z=x+2$ ;  $2 \leq x \leq 5$ ; and  $0.0005 \leq (a/x) \leq 0.02$ .

4. The backlight panel of claim 1, further comprising an air gap arranged between the bottom surface of the diffusion plate and the reflection sheet.

5. The backlight panel of claim 4, wherein light emitted from the white light emitting diodes is mixed together in the air gap before being emitted directly onto the bottom surface of the diffusion plate.

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6. The backlight panel of claim 1, wherein the green phosphor comprises a thiogallate-based phosphor expressed by the general formula:  $(A_{1-x-y}Eu_x(M^I_{0.5}M^{III}_{0.5})_y)B_2S_4$ , where  $0 < x, y, x+y < 1$ ; A is at least one element selected from the group consisting of Ba, Sr and Ca; B is at least one element selected from the group consisting of Al, Ga and In;  $0.01 \leq x \leq 0.1$ ;  $M^I$  is at least one element selected from the group consisting of Li, Na and K;  $M^{III}$  is at least one element selected from the group consisting of Sc, Y, Lu, Gd and La; and  $0.2 \leq y \leq 0.8$ .

7. The backlight panel of claim 6, wherein the red phosphor comprises an alkaline earth metal sulfide-based phosphor expressed by the general formula:  $A_{x-a}Eu_aGeS_2$ , where A is at

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least one element selected from the group consisting of Ca and Sr;  $z=x+2$ ;  $2 \leq x \leq 5$ ; and  $0.0005 \leq (a/x) \leq 0.02$ .

8. The backlight panel of claim 3, wherein the green phosphor comprises a thiogallate-based phosphor expressed by the general formula:  $(A_{1-x-y}Eu_x(M^I_{0.5}M^{III}_{0.5})_y)B_2S_4$ , where  $0 < x, y, x+y < 1$ ; A is at least one element selected from the group consisting of Ba, Sr and Ca; B is at least one element selected from the group consisting of Al, Ga and In;  $0.01 \leq x \leq 0.1$ ;  $M^I$  is at least one element selected from the group consisting of Li, Na and K;  $M^{III}$  is at least one element selected from the group consisting of Sc, Y, Lu, Gd and La; and  $0.2 \leq y \leq 0.8$ .

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